

**NANO PARTICLE REINFORCED LEAD FREE
Sn–3.0Ag–0.5Cu SOLDER PASTE FOR REFLOW
SOLDERING PROCESS**

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UNIVERSITI SAINS MALAYSIA

2016

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PASTE FOR REFLOW SOLDERING PROCESS**

by

SRIVALLI A/P CHELLVARAJOO

**Thesis submitted in fulfillment of the requirements
for the degree of
Doctor of Philosophy**

July 2016

DECLARATION

I hereby declare that the work reported in this thesis is the result of my own investigation and that no part of the thesis has been plagiarized from external sources. Materials taken from other sources are duly acknowledged by giving explicit references.

Signature:

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Date: 14th July 2016

ACKNOWLEDGEMENTS

One of the most profound learning's of my life is this: the more pain you have to endure on your journey, the sweeter the arrival at your destination; if you want to achieve your highest dreams and overcome your greatest obstacles, prayers is the most powerful medicine that governs the results you seek. I cannot find words to express my gratitude to the ultimate God for blessing me with such a wonderful opportunity to pursue Ph.D program as well completing this research work. I owe my life to God's never ending love and giving me the strength to overcome all the challenges and difficulties I endured throughout this research journey. It gives me great pleasure to appreciate the meditation and yogic power, which really helps me to stay focus and energize all the time.

My road to pursuing the Ph.D program mixed with a little bit of bitterness, hardships and frustration but mostly with trust, encouragement and motivation. It has enriched me with experiences, broadened my knowledge perspective and motivated me to strive for excellence in research. All these were not achieved single-handedly. It will be not enough to express my gratitude in words to those people who helped me, though, I still like to record abundant thanks to all the precious souls for their kind assistance, guidance and support.

Firstly, I would like to express my deepest and sincere gratitude to my honorific supervisor, Professor Ir. Dr. Mohd Zulkifly Abdullah, Dean, School of Aerospace Engineering, Engineering Campus, Universiti Sains Malaysia, for all his valuable guidance and support throughout this research. He patiently supervise and offered me ample of advice to ensure I do not project away from my research scope. His wide knowledge, valuable suggestions, and encouragement have been of

great value for me. I have learned a lot from him and without his backing, I could not have completed my dissertation successfully.

Thereafter, I wish to express my warm and sincere thanks to Dean, Prof. Dr. Zainal Alimuddin Zainal Alauddin, Professor Dr. Mohd Zaidi Mohd Ripin and all the staff of the School of Mechanical Engineering, for their countless efforts and helps in concluding my research work. I would also like to thank Mr. Zambri Samsudin (Sr. Manager-Engineer Technology Services (Asia)), Mr. Yusuf and Mr. Fakhrozi Che Ani (Sr. Advanced Technology Engineer (Asia)) for their support and help to conduct some research work at their industry (Jabil Circuit Sdn. Bhd). Next, I would like to express my appreciation to my ex-colleague, Dr. C.Y.Khor (Senior Lecturer, Faculty of Engineering Technology (FETech), Universiti Malaysia Perlis) for his valuable time and suggestions in discussions.

Then, I gratefully acknowledge my beloved family members for their unwavering love and support. Who am I today is all because the strength in love and care of my parents. I want to express my deepest gratitude to my dear mother Madam Kanagammah and my dear father late Mr. Chellvarajoo for their priceless prayers and inseparable support. I lost my father during my research program. Though, it's a great lost for me, I motivates myself to work harder and give my very best so I could pay tribute to him.

Above all, my loving, supportive, encouraging, and patient husband, Mr. Jeevan Raj whose faithful support during the final stages of this Ph.D is much appreciated. He always has been there for me providing sincere support and encouragement throughout this project work. Furthermore, I would like to convey my sincere and heartfelt thanks to all my family, wherever they are, particularly my

siblings Mr. Balamurugan and Ms. Dehvigah, my family in-laws, and friends who are supported me all the time.

Finally, I am grateful to the Ministry of Higher Education Malaysia (MOHE) for allocating MyBrain15 scholarship to pursue Ph.D studies. Last but not least, I would like to take this opportunity to forward my thanks and appreciation to every individual for their constant supports, encouragements, and helps, directly and indirectly, in accomplishing my dissertation. All good things are worth appreciating and thanking for. Thank you to all beautiful hearts.

Srivalli A/P Chellvarajoo

July 2016

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